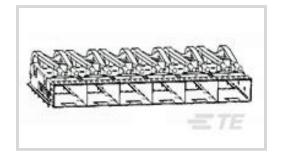
2227732-1 - ACTIVE

TE Internal #: 2227732-1 SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 32 Gb/s, Internal/External EMI Springs, zSFP+ Thermally Enhanced, With Lightpipe, 1 x 6 View on TE.com >



Connectors > Pluggable IO Connectors & Cages > SFP, SFP+ & zSFP+ > zSFP+ Cage Assembly: EMI Springs



Pluggable I/O Product Type: Cage Assembly

Data Rate (Max): 32 Gb/s

EMI Containment Feature Type: Internal/External EMI Springs

Pluggable I/O Applications: **zSFP+ Thermally Enhanced**

Lightpipe Options: With Lightpipe

All zSFP+ Cage Assembly: EMI Springs (25)

Features

Product Type Features

Form Factor	zSFP+
Cage Туре	Ganged
Pluggable I/O Product Type	Cage Assembly
Lightpipe Options	With Lightpipe
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Port Matrix Configuration	1 x 6
Number of Ports	6
Electrical Characteristics	
Data Rate (Max)	32 Gb/s
Termination Features	
Termination Post & Tail Length	2.05 mm[.081 in]
Termination Method to Printed Circuit Board	Through Hole - Press-Fit
Mechanical Attachment	
Connector Mounting Type	Board Mount

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Housing Features	
Cage Material	Nickel Silver Alloy
Dimensions	
PCB Thickness (Recommended)	2.25 mm[.089 in]
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Heat Sink Compatible	No
For Use With Pluggable I/O Products	zSFP+ SMT Connector
Pluggable I/O Applications	zSFP+ Thermally Enhanced
Circuit Application	Signal
Packaging Features	
Packaging Method	Tray
Other	
EMI Containment Feature Type	Internal/External EMI Springs

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not applicable for solder process capability

Product Compliance Disclaimer

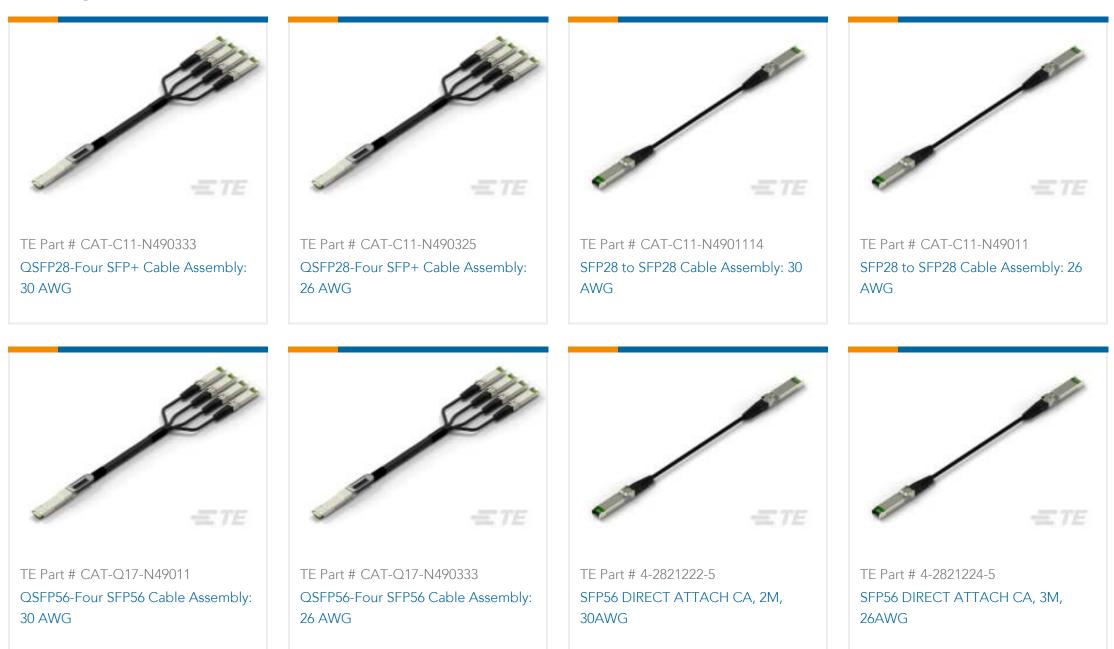
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products

SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 32 Gb/s, Internal/External EMI Springs, zSFP+ Thermally Enhanced, With Lightpipe, 1 x 6



will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts





Customers Also Bought



SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 32 Gb/s, Internal/External EMI Springs, zSFP+ Thermally Enhanced, With Lightpipe, 1 x 6







Documents

Product Drawings

zSFP+ 1x6 Cage Assembly, Press-Fit

English

CAD Files 3D PDF

3D

Customer View Model ENG_CVM_CVM_2227732-1_B.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2227732-1_B.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2227732-1_B.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages zSFP+ Interconnect Brochure

English

Product Specifications
Application Specification

English

Instruction Sheets Instruction Sheet (U.S.)

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English

Instruction Sheet (U.S.)

English